

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	8	("5583378" "5710459" "5869889" "5895967" "5986340" "6023098" "6032355" "6032362").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/26 09:06
L3	4	(substrate or package or packaging or circuit adj board or wiring near board or pcb or pwb or interposer) near3 (strip) and drop near3 (heatsink or heat adj sink)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/26 09:16
L4	352	(substrate or package or packaging or circuit adj board or wiring near board or pcb or pwb or interposer) near3 (strip) and (heatsink or heat adj sink) near5 (ic or chip or die or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/26 09:16
L5	45	(substrate or package or packaging or circuit adj board or wiring near board or pcb or pwb or interposer) near3 (strip) and (heatsink or heat adj sink) near5 (above or top or contacting or touching or adjacent or nearby or over or upon) near3 (ic or chip or die or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/26 09:17
L6	109	("20020079570" "3908075" "3942245" "4501960" "4674175" "4701781" "4975765" "5023202" "5041395" "5122860" "5157475" "5172213" "5175612" "5285105" "5334857" "5366933" "5420460" "5474957" "5482736" "5482898" "5485037" "5556807" "5596231" "5596485" "5620928" "5650593" "5672548" "5672909" "5679978" "5693572" "5708567" "5729432" "5736785" "5789813" "5796163" "5807768" "5854511" "5867368" "5874321" "5886397" "5894108" "5900676" "5939784" "5940271" "5949655" "5950074" "5962810" "5981314" "5982621" "5986336" "5986340" "6011304" "6028354" "6034429" "6049125" "6069023" "6081028" "6081029" "6091603" "6092281" "6097101" "6104086" "6111324" "6117193" "6117705" "6127724" "6143588" "6150193" "6162849" "6163458" "6165612" "6191360" "6196002" "6198163" "6206997" "6208519" "6212070" "6214644" "6219238" "6222263" "6228676" "6229200" "6229702" "6236568" "6242281" "6246566" "6258629" "6265771" "6266197" "6274927" "6281241" "6281568" "6285075" "6291884" "6294100" "6294830" "6326678" "6395578" "6396143" "6429048" "6429508" "6433360" "6444498" "6452255" "6458626" "6498099" "6507102" "6552417" "6556740").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/26 10:09
L7	301	257/706.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/26 10:29
L8	136	257/707.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/26 10:38
L9	372	257/712.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/26 11:16
L10	79	257/796.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/26 11:20
L11	204	438/122.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/26 11:26
L12	4	"5726079".pn. "5949137".pn. "6410988".pn. "6444498".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/26 11:27

L13	20	(US-20020006718-\$ or US-20020149092-\$ or US-20020180035-\$ or US-20020187590-\$ or US-20030071348-\$ or US-20030092221-\$ or US-20030203539-\$ or US-20040195701-\$ or US-20050003585-\$ or US-20050012203-\$).did. or (US-5311060-\$ or US-6228683-\$ or US-6323066-\$ or US-6734552-\$ or US-6853070-\$ or US-6861750-\$ or US-6933176-\$ or US-6709895-\$ or US-6559537-\$ or US-6432749-\$).did.	US-PGPUB; USPAT	OR	ON	2005/08/26 11:28
S1	96	438/111.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 16:59
S2	132	438/112.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 10:19
S3	1066	(chip or die or integrated adj circuit or ic) and (substrate or leadframe or frame or package or packaging or housing) near2 (strip or tape) and (heatsink or (heat or thermal\$2) near2 (sink or spread\$3)) and (encapsulat\$4 or encapsulant or molding or mold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 10:23
S4	278	(chip or die or integrated adj circuit or ic) and (substrate or leadframe or frame or package or packaging or housing) near2 (strip or tape) and (heatsink or (heat or thermal\$2) near2 (sink or spread\$3)) and (encapsulat\$4 or encapsulant or molding or mold) near6 (open or expos\$4 or uncover\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:06
S5	23	(substrate or leadframe or frame or package or packaging or housing) near2 (strip or tape) and (heatsink or (heat or thermal\$2) near2 (sink or spread\$3)) near6 (chip or die or ic or integrated adj circuit) near10 (thermal near interface or thermal\$2 near adhesive or tim) and (encapsulat\$4 or encapsulant or molding or mold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:33
S6	112	(substrate or leadframe or frame or package or packaging or housing) near2 (strip or tape) and (heatsink or (heat or thermal\$2) near2 (sink or spread\$3)) near6 (chip or die or ic or integrated adj circuit) near20 ((thermal\$2 or heat\$2) near2 (interface or adhesive) or tim)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:34
S7	431	(substrate or package or packaging or circuit adj board or wiring near board or pcb or pwb or interposer) near3 (strip) and (chip or die or integrated adj circuit or ic) near5 ((heat or thermal\$3) near (sink or spreader or spreading or dissipat\$4 or conduct\$4) or heatsink) and (encapsul\$4 or molding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 17:02
S8	137	(substrate or package or packaging or circuit adj board or wiring near board or pcb or pwb or interposer) near3 (strip or panel) and (chip or die or integrated adj circuit or ic) near5 ((heat or thermal\$3) near (sink or spreader or spreading or dissipat\$4 or conduct\$4) or heatsink) same (encapsul\$4 or molding) and (ball near grid or solder near ball or solder near bump or bga)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/26 09:15
S9	1	"6933176".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 17:07
S10	30	("20010015492" "20020005578" "20020006718" "20020180035" "20020185734" "20030034569" "5172213" "5311060" "5339216" "5444025" "5493153" "5610442" "5639694" "5650663" "5679978" "5705851" "5736785" "5773362" "5877552" "5977626" "5986885" "6037658" "6236568" "6251706" "6323066" "6414385" "6462405" "6525421" "6631078" "6656770").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/25 17:07